

JFP Model PP-One

The machines which require minimal training to operate



Manual / Semi Auto DIE BONDER

The Manual Sorter PP-One model is designed for accurate Picking and Placement of delicate devices as Laser Diodes and Laser Bars.



The machine will pick the components from wafer hoops to place them into GelPack or Waffle Packs...

The machine provides a simple solution for epoxy stamping bonding, using a double head combination.

Standard zoom magnification is continuously adjustable.... It achieves high accuracy placement using required adjustable magnification.

PP-One is a robust, and reliable mechanical concept, easy to use, flexible, requires only minimum training to operate

SYSTEM

- Table Top machine
- Automatic Transfer Arm
- Vertical Z motion
- Tool holders compatible with PP5 serie
- UPH : 500 P/H

DIE & SUBSTRATE

- Minimum die size 150*150µm
- Maximum die size 30 mm
- Substrate, WafflePack, Up to 350 mm

VISION-ALIGNMENT SYSTEM

- Field of view: Optical zoom, 2,9 up to 33 mm
- Optical Zoom : 20X up to 180X
- Vertical vision of die and package
- 2 CCD Color camera high resolution
- 2 Digital Adjustable Crosshair
- Fine Video Offset adjustments
- 2 TFT monitor 17"
- LED lightings
- Direct Placement

TABLE

- Manually handled
- Height adjustable workholders
- Working area : 400 x 350 mm
- PARAMETERS
- Low Picking Force: 5 gr
- Place Force adjustable

OPTIONS

- Dual head for stamping/dispensing
- Stamping, rotary dish and adjustable blade
- Heater worholder
- Eject system from wafer (Rings or Hoops)
- Compatible for Laser Diodes and long Laser Bars
Wafer Expander solution
to be provided separately

TECHNICAL SPECIFICATION

Power: 100 / 230VAC 150watt
Vacuum: 70%
Dimensions: 650*620*450mm
Weight: 25 kg

JFP Microtechnic® is a registered trademark

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